



WE BUILD MORE THAN WAFERS. WE BUILD TRUST.

CORPORATE OVERVIEW

TOWERJ&L

THE GLOBAL SPECIALTY FOUNDRY LEADER

Tower Semiconductor Ltd. (NASDAQ: TSEM, TASE: TSEM), and its fully owned U.S. subsidiary **Jazz Semiconductor**, operate collectively under the brand name **TowerJazz**, the global specialty foundry leader, manufacturing integrated circuits with geometries ranging from 1.0- to 0.13-micron in a variety of advanced CMOS technologies, while also providing complementary technical services and design support.

TowerJazz provides industry leading design enablement tools to allow complex designs to be achieved quickly and more accurately and offers a broad range of customizable process technologies including SiGe, BiCMOS, Mixed-Signal and RFCMOS, CMOS Image Sensor, Power Management (BCD), and Non-Volatile Memory (NVM) as well as MEMS capabilities.

The company's technical acumen and its dedication to quality customer service attracts customers from target markets as diverse as consumer electronics, personal computer and office equipment, communications, automotive and airborne, industrial, professional photography and medical products.

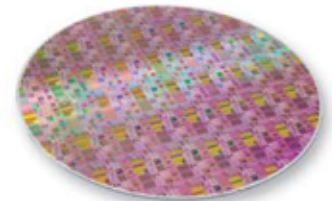
To provide world-class customer service, TowerJazz maintains two manufacturing facilities in Israel and one in the U.S. with additional capacity available in China through manufacturing partnerships.

TECHNOLOGY OVERVIEW

TowerJazz offers wafer foundry services providing the widest range of customizable CMOS specialty processes and proven design enablement tools for the manufacture of optimized integrated circuits (ICs). Our process technologies with geometries ranging from 1.0- to 0.13-micron include: SiGe, BiCMOS, Mixed-Signal & RFCMOS, CMOS Image Sensor (CIS), Power Management (BCD), Digital CMOS, Embedded Non-Volatile Memory (NVM) as well as MEMS capabilities integrated with CMOS. These modular processes are tailored to meet our customers' precise specifications for the most cost-effective and versatile solutions. We offer a proven design enablement platform for unprecedented accuracy and first-time success including silicon verified and scalable device models and robust physical design tools.

We are well recognized for our SiGe, BiCMOS and RFCMOS. We are the only pure play foundry with multi-fab SiGe capacity for the manufacture of high performance analog (HPA) products. Our SiGe process is often competitive with GaAs, offering as much as 40% lower die cost. We have industry leading, Bipolar-CMOS-DMOS (BCD) processes for use in complex power management chips and a leading CMOS Image Sensor (CIS) technology to meet the growing demand for optical sensors used in consumer, industrial, medical and automotive applications. We offer MEMS solutions coupled with high volume 200mm CMOS manufacturing to address complex wireless and consumer electronics markets. We provide on-shore foundry services to the Aerospace and Defense industry for Large Die, ROICs and millimeter wave applications. In addition, we offer Transfer Optimization and Process Services (TOPS) to IDMs and fabless companies to expand capacity or provide second sourcing.

All of these process technologies are manufactured on either 150mm or 200-millimeter wafers in our world-class fabrication facilities which have achieved quality certifications for Environmental Management, Health & Safety, Information Security, and Automotive standards.



SPECIALTY TECHNOLOGIES/DESIGN ENABLEMENT

High Performance Analog (HPA)

We are the industry's only pure play foundry with multi-fab SiGe BiCMOS capability for the manufacture of HPA products optimized for high-speed and low power devices for today's high-frequency networking and wireless communications. To meet our customers' needs to deliver competitively differentiated products, we offer customizable design kits geared for high frequency devices. To minimize design spins, we leverage our design enablement and HPA application expertise for first-pass success. Our SiGe process utilizes state-of-the-art processing technology in order to drive high speed performance while providing an ideal platform for logic and analog integration.

Radio Frequency (RF)

Our commercial SiGe BiCMOS and RFCMOS technologies enable high speed consumer applications including cellular/front end PA and Switch modules, TV tuners, and radio transceivers in cell phone, WLAN, WiMAX and GPS devices. Our RF technology allows customers to acquire best-in-class performance very cost effectively for the highest ROI possible of any alternate solution. This offering achieves noise and power performance that is competitive with GaAs while offering as much as 40% lower die cost. Our RFCMOS offering is desirable for the most cost-sensitive RF devices. Our leadership technology provides the industry's best cost and performance-optimized RF solution and meets our customers' requirements for a fast and efficient RF design flow.

Power Management (PM)

Our industry leading Bi-polar-CMOS-DMOS (BCD) process is used in complex power management chips including driver ICs, battery and portable power management, power control for PCs, Class-D audio amplifiers, and other consumer, communications and computing applications. Our customizable LDMOS (20V to 80V) process provides design optimization and the lowest die size at any given breakdown voltage. Our roadmap includes devices to 700V for the next generation digital lighting. Our platform offers maximum flexibility, enabling our customers to create cost-effective products at any desired level of integration and achieve first-pass success for faster time-to-market. The integration of Non-Volatile Memory (NVM) provides significant differentiation and cost effectiveness for enhanced power management solutions.

CMOS Image Sensor (CIS) Technology

Our advanced and proven CMOS image sensor technology is intended to meet the established growing demand for optical sensors used in consumer, industrial, medical and automotive applications. Our lengthy experience in the imaging field, combined with our own CMOS technology developed in-house, enables best-in-class customized designs. Our skilled experts support the customization of pixels per project needs and our superior performance (dark current, low noise and dynamic range) enables a rich offering for various digital imaging applications. We have demonstrated leading CIS technology for high end cameras and we are a proven leader in X-ray CMOS image sensors with the largest market share. Our long-term R&D investment keeps us at the cutting edge.

Micro-Electro-Mechanical Systems (MEMS)

Our world-class "Foundry MEMS enablement" solutions integrate custom MEMS with our specialty processes to address complex wireless and consumer electronics markets. We are focused on a collaborative partnership model and apply our foundry experience, silicon MEMS processes and customer oriented team to enable the successful and rapid implementation of both 150mm and 200mm MEMS manufacturing, including both prototype and ramp to volume production. We continue to augment our portfolio of specialty silicon technology adding MEMS manufacturing to our existing suite of analog and RF CMOS, high speed SiGe, and high voltage technology enhancing the ability of our customers to create and bring to market more highly integrated analog products.

Complementary Metal Oxide Semiconductor (CMOS)

With our CMOS offering, we support designers who are seeking volume production at 0.18-, 0.16-, and 0.13-micron nodes. We provide a flexible and highly customizable process, a world renowned modeling kit, and best-in-class PDK support to achieve industry-leading yields, maximum performance, cost-effectiveness and fast time-to-market. We offer a wider 0.13-micron process technology than competitive offerings and our unique ability to modify the process in a very short time allows us to meet our customers' aggressive timelines. Decades of CMOS technology expertise enables us to deliver an optimum solution to our customers with outstanding service and support. We are able to meet high volume needs of more than 50K wafer/month capacity.

Aerospace and Defense (A&D)

We supply strategic, on-shore foundry services for critical Aerospace and Defense applications through our industry and segment expertise. We have extensive capabilities bringing the broad range of commercially available technologies and services to the A&D community. We are the single supplier serving the widest range of A&D specific technologies including Large Die, ROICs, MEMS, and millimeter wave, among others. The A&D business model has been developed to support various levels of engagement from very low volume development and early prototype needs to high volume production. We also support all our customer ITAR needs and requirements and participate in numerous government programs and partnerships.

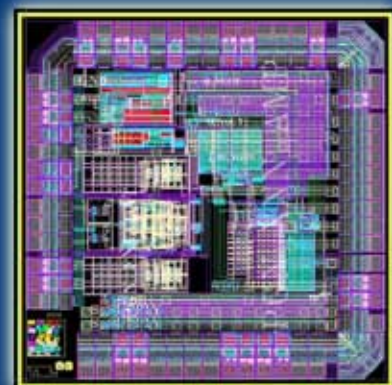
Transfer Optimization and Process Service (TOPS)

We offer process transfer services for Integrated Device Manufacturers (IDMs). We also serve fabless companies with their own process flows who need to expand capacity or secure additional manufacturing sites, or need to progress from an R&D line to a production line. Our process services include development, transfer, and extensive optimization as defined by customer needs. With our world-class engineering team, well established transfer methodologies, and vast manufacturing experience, we guarantee fast time-to-market and low risk services. With a combination of well known IP protection and capacity flexibility commitment, we guarantee customer confidence and satisfaction.

Design Enablement (DE): Tools and Models

We are recognized for our industry leading models and tools which give our customers a significant competitive market advantage with first time design success, optimal performance, and the shortest time-to-market at reduced cost. Our extensive design enablement infrastructure provides an environment optimized for analog and RF designs. This includes silicon verified and highly scalable device models and robust physical design tools for up front design optimization. Our powerful and efficient tools enable unprecedented accuracy in device models and our unparalleled customer support at every stage of the design flow ensures confidence in designs at near zero risk.

0.18 μ m
RF





HISTORY OVERVIEW

Tower Semiconductor and Jazz Technologies merged in September 2008 in a stock for stock transaction. In November 2009, the combined companies officially launched as TowerJazz. The merger has provided several key benefits: increased global capacity, a larger customer base, a more comprehensive product portfolio, and a stronger financial base. We are the fastest growing pure play specialty foundry in the past three years.

Tower Semiconductor was founded in 1993, with the acquisition of National Semiconductor's 150-mm wafer fabrication facility. Tower became a public company in 1994 and shares are traded on NASDAQ (TSEM) and Tel Aviv Stock Exchange (TSEM). Since that time, we have significantly modernized the facility (Fab 1) in Migdal Haemek, Israel and offer process geometries ranging from 1.0-micron to 0.35-micron including CMOS image sensors, embedded flash and mixed-signal technologies. In January 2001, we constructed an adjacent, state-of-the-art facility (Fab 2), designed to operate in geometries of 0.18-micron and below, using advanced CMOS technology.

Jazz Semiconductor was formed in 2002 as a spinoff of Conexant Systems, a fabless semiconductor company that spun-off from Rockwell Semiconductor in 1999. Jazz inherited the Newport Beach, California 200mm fabrication facility and the company's legacy including the establishment of industry leading SiGe, BiCMOS and MEMS technologies and the cultivation of a strong design support organization. In addition, Jazz expanded upon its heritage for on-shore, specialized foundry services focused on the Aerospace and Defense industry.

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